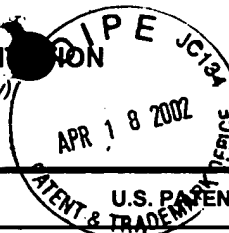


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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
WA	1.	6,011,304	1/2000	Mertol	257	706	
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							YES	NO
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WA	13.	R. Hundadi, et al., "High Thermal Conductivity Greases,: pp. 28-32, Advanced Packaging, April 1999.						
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EXAMINER	DATE CONSIDERED
<i>[Signature]</i>	12/02

*EXAMINER. Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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